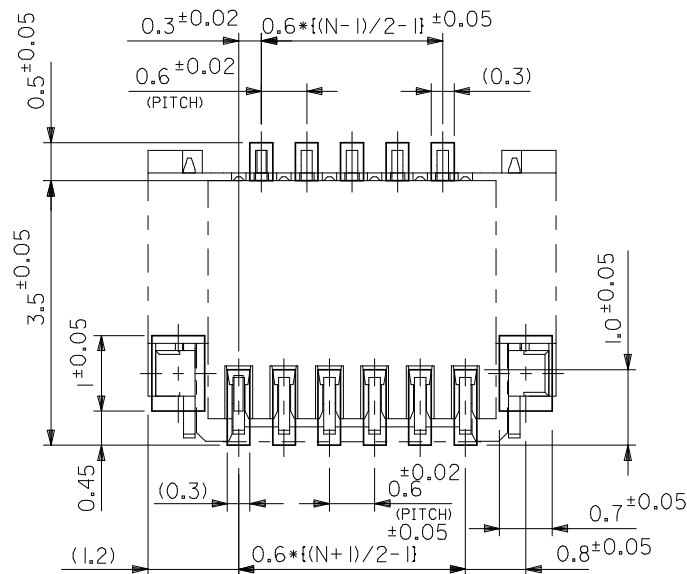


6.6	5.4	6.0	8.4	500797-2160	21
D	C	B	A	MATERIAL NO.	CIRCUIT
				500797-**60	MODEL No.

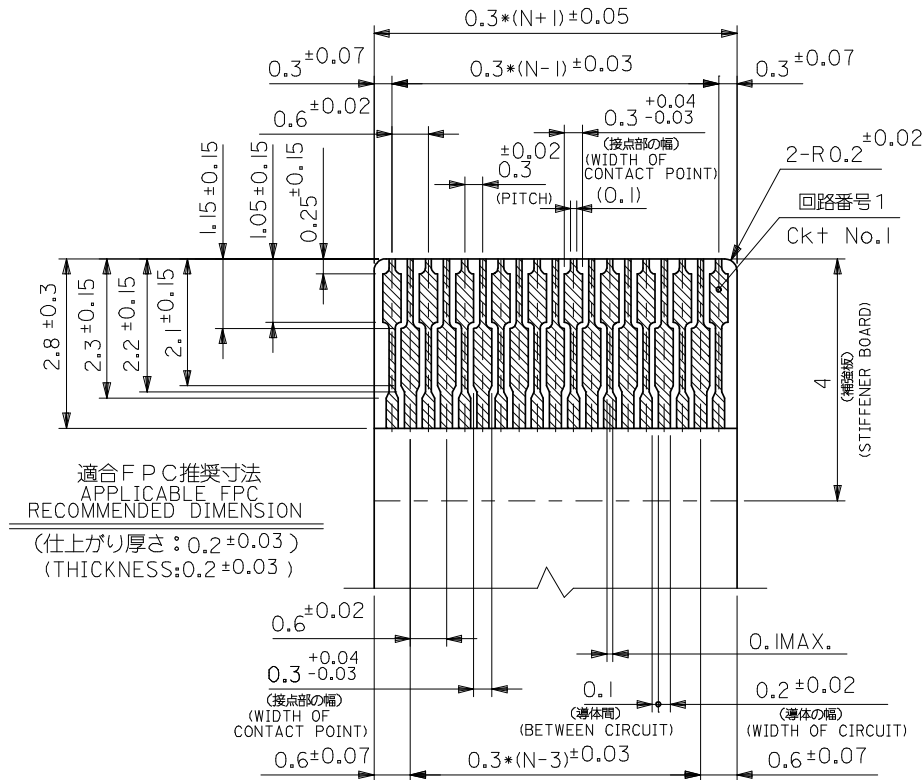
REVISED EC NO.: J2009-0416 DRWN: MABEI 2008/08/21 CHKD: HAYASHI 2008/08/25 APPR: NUKITA 2008/08/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TKON	DATE 2007/01/18	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY YMAEDA	DATE 2007/01/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2007/01/18	MATERIAL NO. SEE TABLE DOCUMENT NO. SD-500797-007 SHEET NO. 1 OF 2		
A	DESCRIPTION ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参考基板レイアウト図  
(マウント面)  
(MOUNTING SIDE)

注記 NOTES

- 使用材料 MATERIAL  
 ハウジング : 液晶ポリマー ガラス充填 UL94V-0  
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0  
 アクチュエータ : 46 ナイロン ガラス充填 UL94V-0  
 ACTUATOR : 46 NYLON (GLASS FILLED) UL94V-0  
 ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ  
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.  
 金具 : リン青銅 (t=0.15), ニッケル下地スズメッキ  
 FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING.
- ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面  $\square$  に対し、上方向 0.1MAXIMUM 下方向 0.15MAXIMUM とする。又、相互のバラツキ量は 0.1MAXIMUM とする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM  $\square$   
 UPPER DIRECTION : 0.1 MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.  
 OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM.



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.2±0.03)  
(THICKNESS: 0.2±0.03)

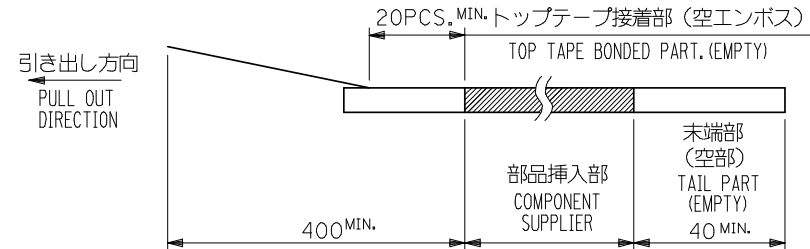
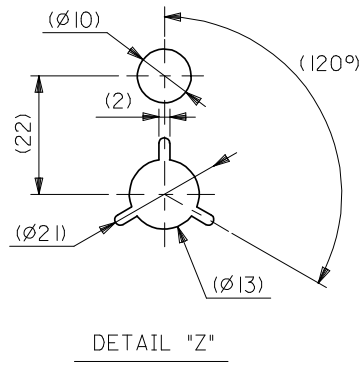
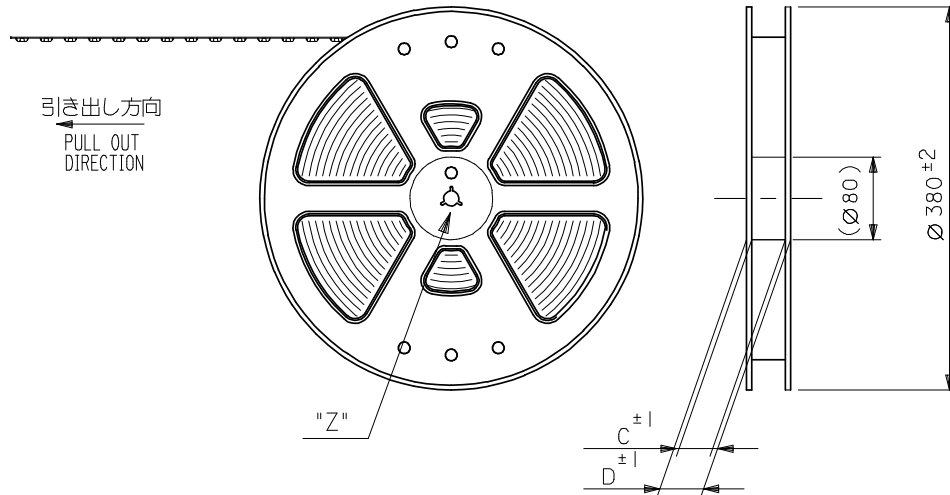
FPCについて:  
 打抜き方向は導体側から補強板側を推奨いたします。  
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。  
 補強フィルム材質はポリイミドを推奨します。  
 接着剤は熱硬化接着剤を推奨します。

ABOUT FPC  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
 RECOMMENDED CONDUCTOR SPEC :  
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

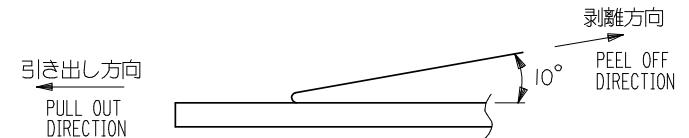
REVISED EC NO: J2009-0416 DRWN: MWABEI 2008/08/21 CHKD: HAYASHI 2008/08/25 APPR: NUKITA 2008/08/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.	
				MM ONLY		---	METRIC	500797-xx60	
				DRAWN BY DATE		TITLE			
				CHECKED BY DATE		0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-			
A	REVISION	10 UNDER	±0.2	T. KON	2007/01/18	molex MOLEX INCORPORATED			
		10 OVER 30 UNDER	±0.25	YMAEDA	2007/01/18				
		30 OVER	±0.3	NUKITA	2007/01/18				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-500797-007		SHEET NO. 2 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

NOTES

- 製品詳細寸法については図面 SD-500797-007 を参照下さい。  
RE DETAILED DIMENSION, SEE SD-500797-007
- 梱包数量：3000個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

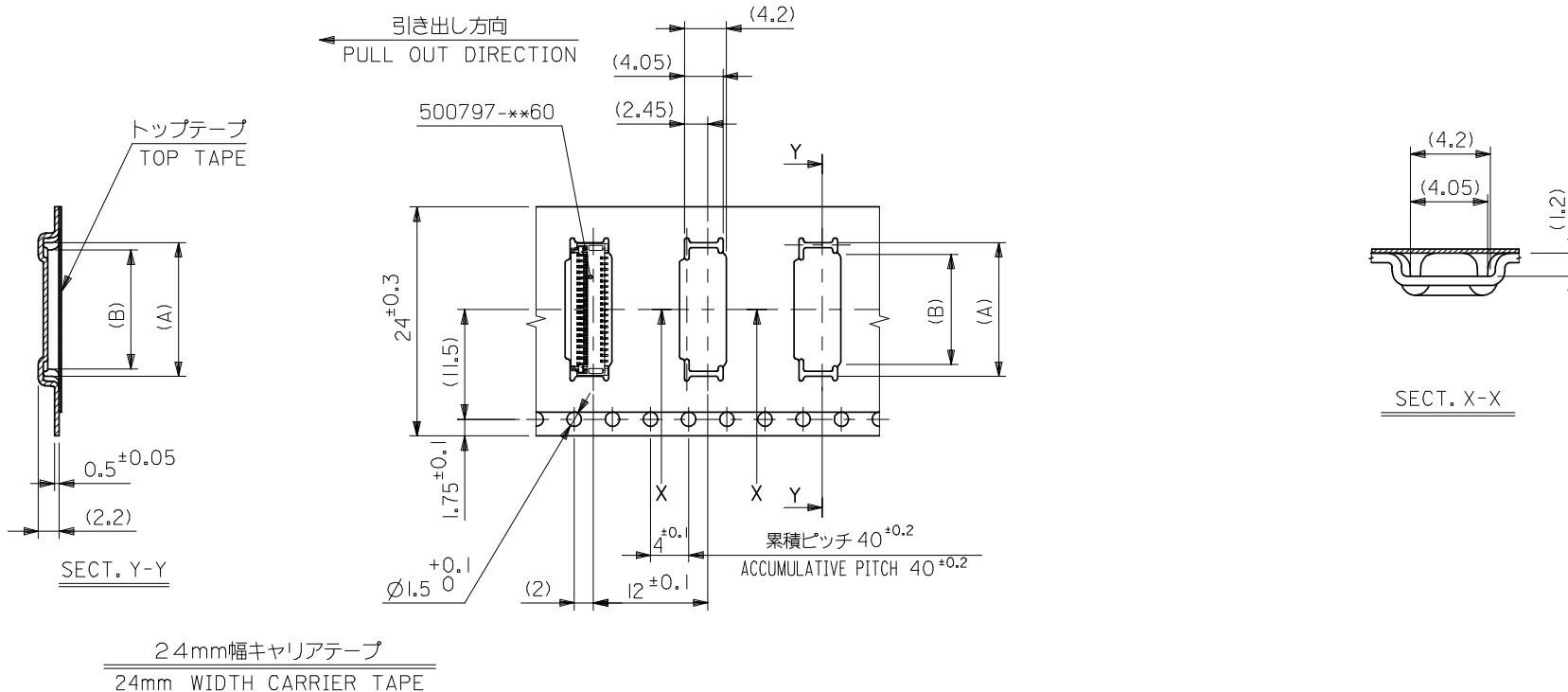


- トップテープの剥離強度：0.1N ~ 1.3N(10.2gf ~ 132.6gf)  
(剥離方向は下図参照)  
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG,)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料(MATERIAL)  
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)  
トップテープ(TOPTAPE)：PET, PE, PEF  
リール(REEL)：ポリスチレン(PS) <リサイクル材含む>  
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- C寸法は SHEET 2 ~ 3 を参照下さい。  
SEE SHEET 2 ~ 3 (DIMENSION C).
- 欠品無きこと。  
THERE SHALL BE NO MISSING PRODUCTS.

REVISED EC NO: J2009-0416 DRWN:MABEL 2008/08/21 CHKD:MIYASHI 2008/08/25 APPR:NUKITA 2008/08/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	500797-**95	MODEL NO.
	10 UNDER	±0.2	DRAWN BY TKON	DATE 2007/01/18	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 OVER 30 UNDER	±0.25	CHECKED BY YMAEDA	DATE 2007/01/18	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2007/01/18	MOLEX INCORPORATED	
DESCRIPTION	ANGULAR ±3 °	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-500797-008		SHEET NO. 1 OF 2	
REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



24	29.4	25.4	6.4	8.6	500797-2160	500797-2195	21
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	CONNECTOR	製品番号 MATERIAL No.	極数 Ck+
						500797-**95	MODEL No.

REVISED EC NO: J2009-0416 DRWN: MABE   2008/08/21 CHKD: MAYASHI   2008/08/25 APPR: NUKITA   2008/08/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YMAEDA	DATE 2006/06/28	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MTANAKA	DATE 2006/06/28	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2006/06/28	DOCUMENT NO. SD-500797-008		
A	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	SHEET NO. 2 OF 2		
REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						